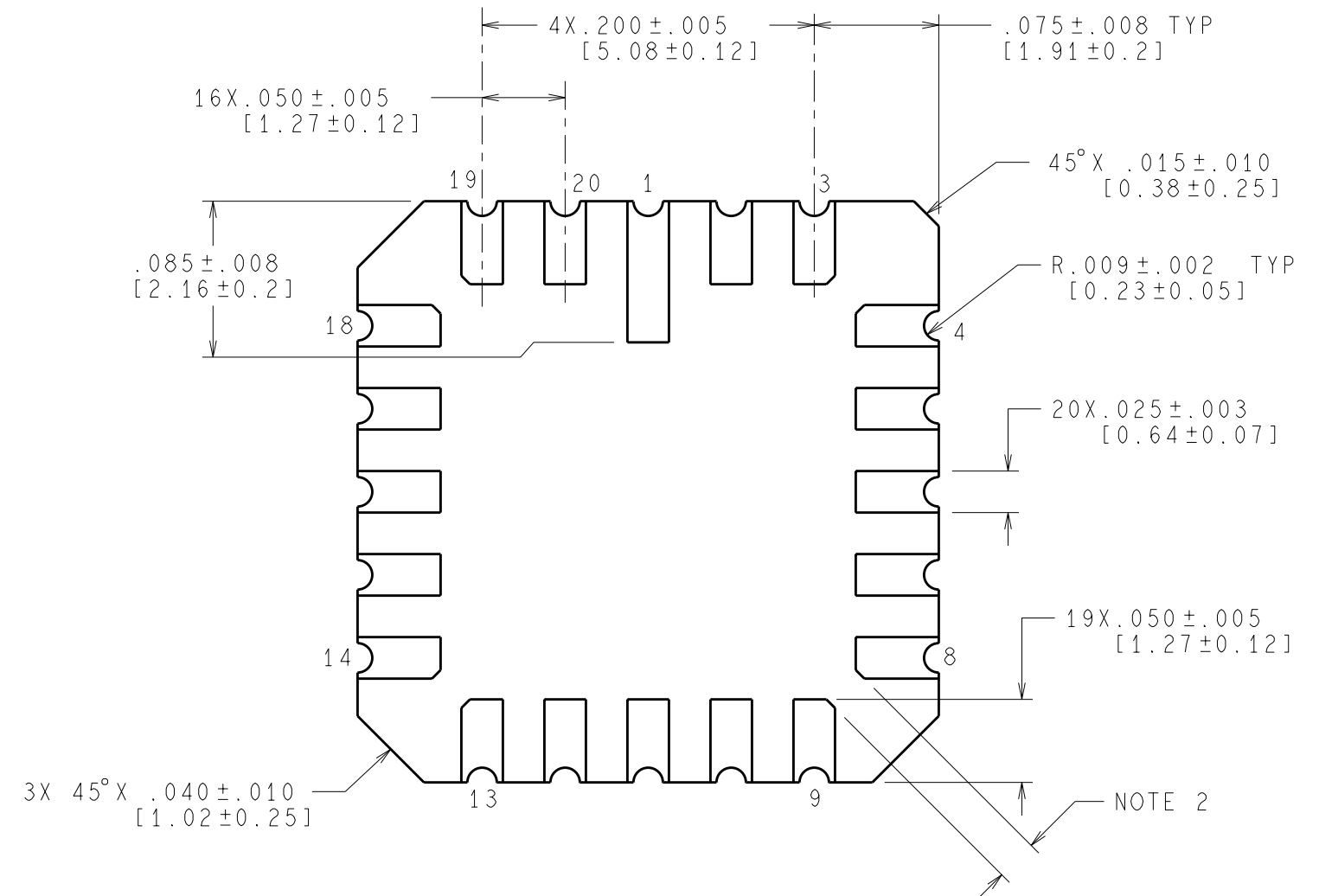
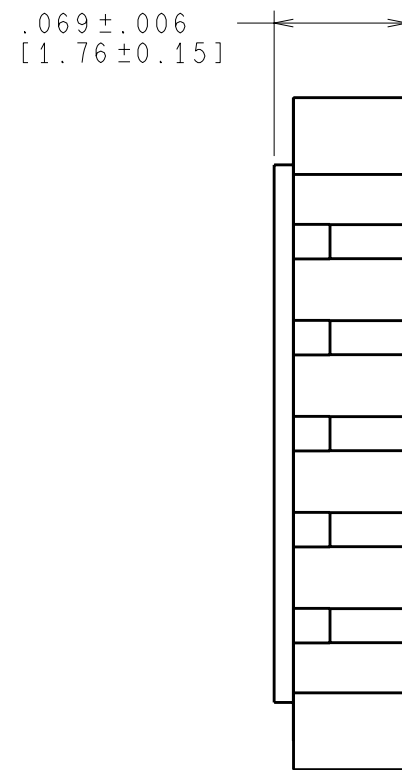
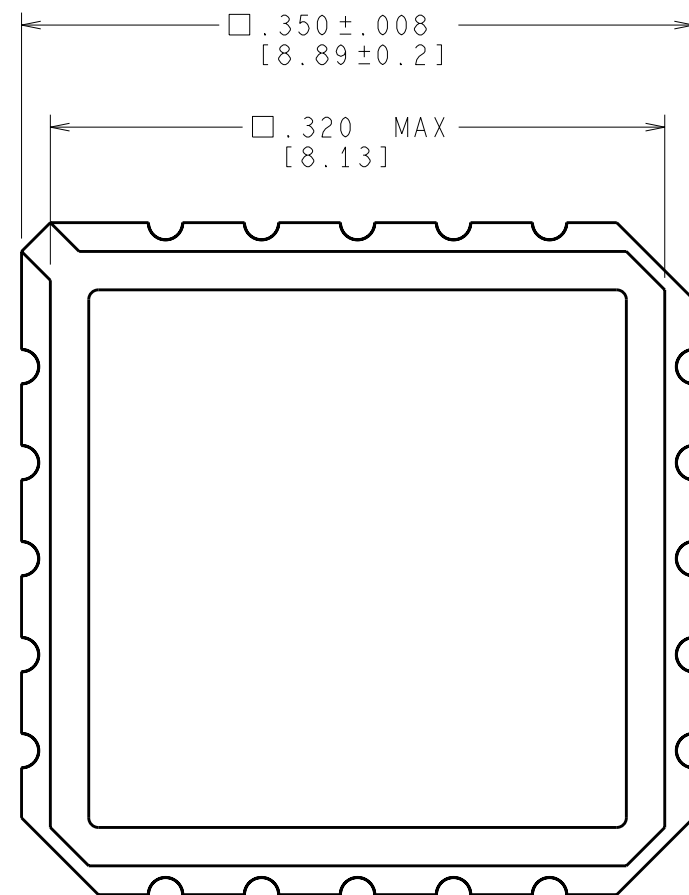


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	REVISE AND REDRAW.	10005	02/10/1994	DEG/AP
F	REVISE NOTES 1 & 3; UPDATE MIL/AERO STAMP; CHANGE DWG FORMAT TO B SIZE.	1394	05/13/2004	MS/ACBS



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL-PRF-38535
CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH: SOLDER DIP.
SOLDER THICKNESS PER LATEST REVISION OF MIL-PRF-38535.
- CORNER PADS MAY HAVE A 45° X .020 IN / 0.51 mm MAXIMUM CHAMFER TO ACCOMPLISH THE .015 IN / 0.38 mm DIMENSION.
- REFERENCE JEDEC REGISTRATION MS-004, VARIATION CB.

APPROVALS	DATE	National Semiconductor	
DRAWN <i>Dwayne Grady</i>	02/10/1994	2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DTG. CHK. <i>THANH LEQUANG</i>	05/13/2004	LEADLESS CHIP CARRIER, TYPE C, 20 TERMINAL	
ENGR. CHK. <i>ALVIN CB SIM</i>	05/13/2004		
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	NTS	B	(SC)MKT-E20A
FORMERLY: N/A	SHEET 1 of 1		REV F